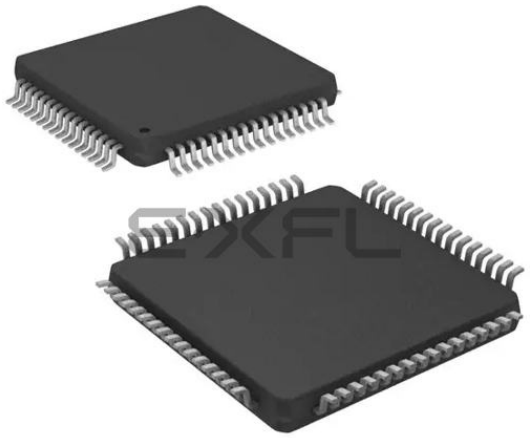
Microchip Technology - DSPIC33FJ64MC506A-E/PT Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc506a-e-pt

TABLE 4-2: CHANGE NOTIFICATION REGISTER MAP FOR dsPIC33FJXXXMCX10A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	—	—	—	—	—	—	—	—	CN23IE	CN22IE	CN21IE	CN20IE	CN19IE	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	—	—	—	—	—	—	—	—	CN23PUE	CN22PUE	CN21PUE	CN20PUE	CN19PUE	CN18PUE	CN17PUE	CN16PUE	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-3: CHANGE NOTIFICATION REGISTER MAP FOR dsPIC33FJXXXMCX08A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	—	—	—	—	—	—	—	—	—	—	CN21IE	CN20IE	CN19IE	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	—	—	—	—	—	—	—	—	—	—	CN21PUE	CN20PUE	CN19PUE	CN18PUE	CN17PUE	CN16PUE	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-4: CHANGE NOTIFICATION REGISTER MAP FOR dsPIC33FJXXXMCX06A DEVICES

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNEN1	0060	CN15IE	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE	CN9IE	CN8IE	CN7IE	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0062	—	—	—	—	—	—	—	—	—	—	CN21IE	CN20IE	—	CN18IE	CN17IE	CN16IE	0000
CNPU1	0068	CN15PUE	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE	CN9PUE	CN8PUE	CN7PUE	CN6PUE	CN5PUE	CN4PUE	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	006A	—	—	—	—	—	—	—	—	—	—	CN21PUE	CN20PUE	—	CN18PUE	CN17PUE	CN16PUE	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

REGISTER 5-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/SO-0[1]	R/W-0[1]	R/W-0[1]	U-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0[1]	U-0	U-0	R/W-0[1]	R/W-0[1]	R/W-0[1]	R/W-0[1]
—	ERASE	—	—	NVMOP<3:0>[2]			
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit

`1` = Initiates a Flash memory program or erase operation. The operation is self-timed and the bit is cleared by hardware once operation is complete
`0` = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit

`1` = Enable Flash program/erase operations
`0` = Inhibit Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit

`1` = An improper program or erase sequence attempt, or termination has occurred (bit is set automatically on any set attempt of the WR bit)
`0` = The program or erase operation completed normally

bit 12-7 **Unimplemented:** Read as ‘`0`’

bit 6 **ERASE:** Erase/Program Enable bit

`1` = Perform the erase operation specified by NVMOP<3:0> on the next WR command
`0` = Perform the program operation specified by NVMOP<3:0> on the next WR command

bit 5-4 **Unimplemented:** Read as ‘`0`’

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits[2]

If ERASE = `1`:
`1111` = Memory bulk erase operation
`1110` = Reserved
`1101` = Erase General Segment
`1100` = Erase Secure Segment
`1011` = Reserved
`0011` = No operation
`0010` = Memory page erase operation
`0001` = No operation
`0000` = Erase a single Configuration register byte

If ERASE = `0`:
`1111` = No operation
`1110` = Reserved
`1101` = No operation
`1100` = No operation
`1011` = Reserved
`0011` = Memory word program operation
`0010` = No operation
`0001` = Memory row program operation
`0000` = Program a single Configuration register byte

Note 1: These bits can only be reset on POR.
2: All other combinations of NVMOP<3:0> are unimplemented.

TABLE 6-1: RESET FLAG BIT OPERATION

Flag Bit	Setting Event	Clearing Event
TRAPR (RCON<15>)	Trap conflict event	POR, BOR
IOPUWR (RCON<14>)	Illegal opcode or uninitialized W register access	POR, BOR
EXTR (RCON<7>)	$\overline{\text{MCLR}}$ Reset	POR
SWR (RCON<6>)	`RESET` instruction	POR, BOR
WDTO (RCON<4>)	WDT time-out	`PWRSAV` instruction, POR, BOR
SLEEP (RCON<3>)	`PWRSAV #SLEEP` instruction	POR, BOR
IDLE (RCON<2>)	`PWRSAV #IDLE` instruction	POR, BOR
BOR (RCON<1>)	BOR, POR	—
POR (RCON<0>)	POR	—

Note: All Reset flag bits may be set or cleared by the user software.

6.1 Clock Source Selection at Reset

If clock switching is enabled, the system clock source at device Reset is chosen, as shown in Table 6-2. If clock switching is disabled, the system clock source is always selected according to the oscillator Configuration bits. Refer to **Section 9.0 “Oscillator Configuration”** for further details.

TABLE 6-2: OSCILLATOR SELECTION vs. TYPE OF RESET (CLOCK SWITCHING ENABLED)

Reset Type	Clock Source Determinant
POR	Oscillator Configuration bits (FNOSC<2:0>)
BOR	
$\overline{\text{MCLR}}$	COSC Control bits (OSCCON<14:12>)
WDTR	
SWR	

6.2 Device Reset Times

The Reset times for various types of device Reset are summarized in Table 6-3. The System Reset signal, $\overline{\text{SYSRST}}$, is released after the POR and PWRT delay times expire.

The time at which the device actually begins to execute code also depends on the system oscillator delays, which include the Oscillator Start-up Timer (OST) and the PLL lock time. The OST and PLL lock times occur in parallel with the applicable $\overline{\text{SYSRST}}$ delay times.

The FSCM delay determines the time at which the FSCM begins to monitor the system clock source after the $\overline{\text{SYSRST}}$ signal is released.

REGISTER 7-12: IEC2: INTERRUPT ENABLE CONTROL REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T6IE	DMA4IE	—	OC8IE	OC7IE	OC6IE	OC5IE	IC6IE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC5IE	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE	SPI2IE	SPI2EIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **T6IE:** Timer6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 14 **DMA4IE:** DMA Channel 4 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 13 **Unimplemented:** Read as ‘0’

bit 12 **OC8IE:** Output Compare Channel 8 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 11 **OC7IE:** Output Compare Channel 7 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 10 **OC6IE:** Output Compare Channel 6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 9 **OC5IE:** Output Compare Channel 5 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 8 **IC6IE:** Input Capture Channel 6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 7 **IC5IE:** Input Capture Channel 5 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

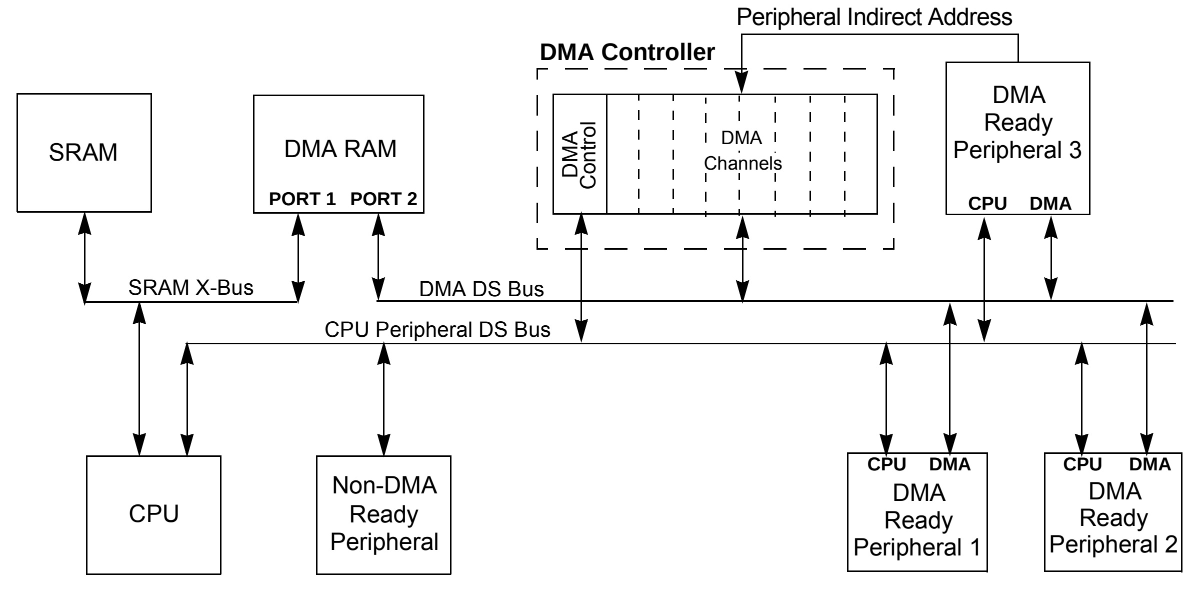
bit 6 **IC4IE:** Input Capture Channel 4 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **IC3IE:** Input Capture Channel 3 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **DMA3IE:** DMA Channel 3 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 3 **C1IE:** ECAN1 Event Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

FIGURE 8-1: TOP LEVEL SYSTEM ARCHITECTURE USING A DEDICATED TRANSACTION BUS



Note: For clarity, CPU and DMA address buses are not shown.

REGISTER 8-7: DMACS0: DMA CONTROLLER STATUS REGISTER 0 (CONTINUED)

bit 3	**XWCOL3:** Channel 3 DMA RAM Write Collision Flag bit `1` = Write collision detected `0` = No write collision detected
bit 2	**XWCOL2:** Channel 2 DMA RAM Write Collision Flag bit `1` = Write collision detected `0` = No write collision detected
bit 1	**XWCOL1:** Channel 1 DMA RAM Write Collision Flag bit `1` = Write collision detected `0` = No write collision detected
bit 0	**XWCOL0:** Channel 0 DMA RAM Write Collision Flag bit `1` = Write collision detected `0` = No write collision detected

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD	PWMMD	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	C2MD	C1MD	AD1MD[1]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **T5MD:** Timer5 Module Disable bit
1 = Timer5 module is disabled
0 = Timer5 module is enabled

bit 14 **T4MD:** Timer4 Module Disable bit
1 = Timer4 module is disabled
0 = Timer4 module is enabled

bit 13 **T3MD:** Timer3 Module Disable bit
1 = Timer3 module is disabled
0 = Timer3 module is enabled

bit 12 **T2MD:** Timer2 Module Disable bit
1 = Timer2 module is disabled
0 = Timer2 module is enabled

bit 11 **T1MD:** Timer1 Module Disable bit
1 = Timer1 module is disabled
0 = Timer1 module is enabled

bit 10 **QEI1MD:** QEI1 Module Disable bit
1 = QEI1 module is disabled
0 = QEI1 module is enabled

bit 9 **PWMMD:** PWM Module Disable bit
1 = PWM module is disabled
0 = PWM module is enabled

bit 8 **Unimplemented:** Read as ‘0’

bit 7 **I2C1MD:** I2C1 Module Disable bit
1 = I2C1 module is disabled
0 = I2C1 module is enabled

bit 6 **U2MD:** UART2 Module Disable bit
1 = UART2 module is disabled
0 = UART2 module is enabled

bit 5 **U1MD:** UART1 Module Disable bit
1 = UART1 module is disabled
0 = UART1 module is enabled

bit 4 **SPI2MD:** SPI2 Module Disable bit
1 = SPI2 module is disabled
0 = SPI2 module is enabled

Note 1: The PCFGx bits have no effect if the ADC module is disabled by setting this bit. In this case, all port pins multiplexed with ANx will be in Digital mode.

NOTES:

15.1 Output Compare Modes

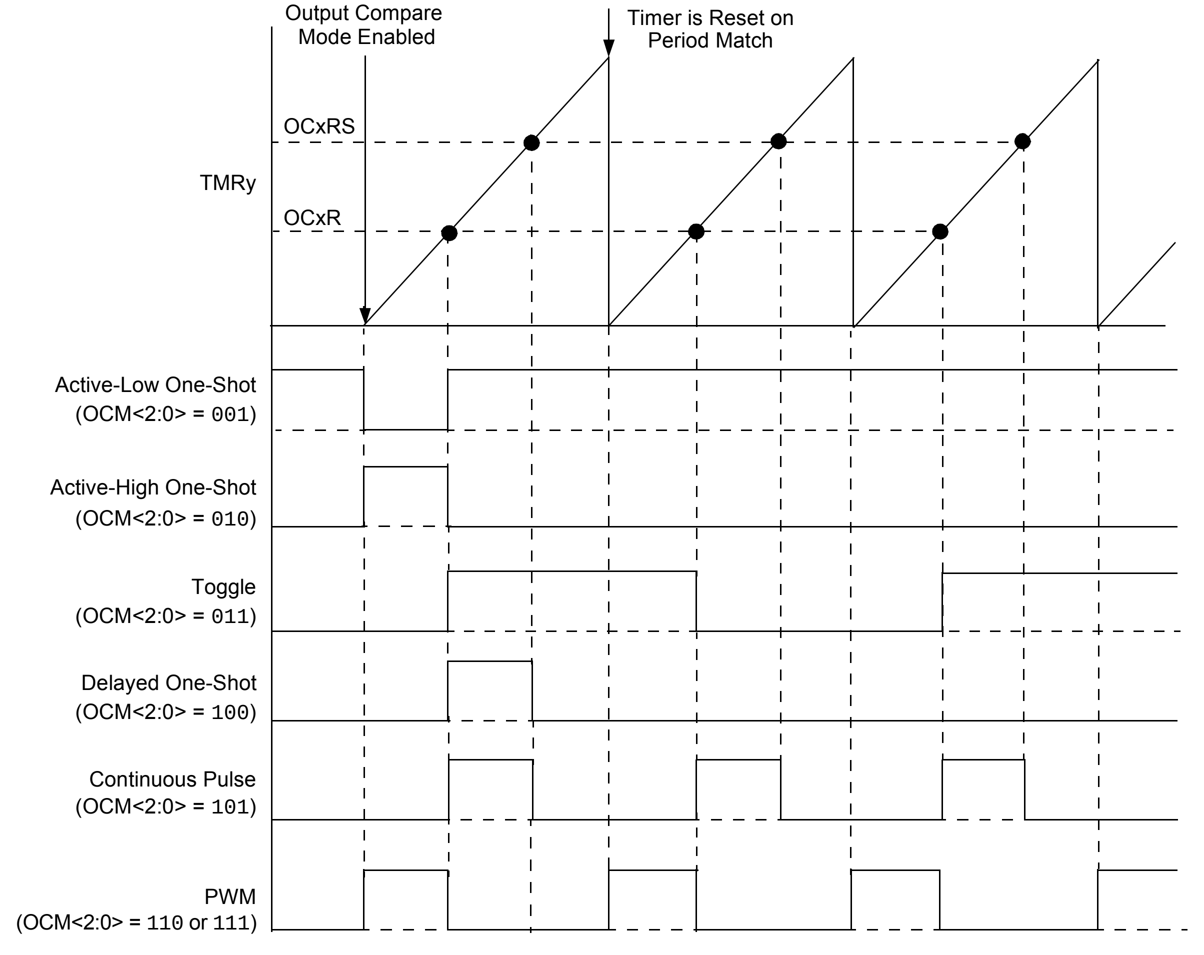
Configure the Output Compare modes by setting the appropriate Output Compare Mode bits (OCM<2:0>) in the Output Compare Control register (OCxCON<2:0>). Table 15-1 lists the different bit settings for the Output Compare modes. Figure 15-2 illustrates the output compare operation for various modes. The user application must disable the associated timer when writing to the Output Compare Control registers to avoid malfunctions.

Note: See **Section 13. “Output Compare”** (DS70209) in the *“dsPIC33F/PIC24H Family Reference Manual”* for OCxR and OCxRS register restrictions.

TABLE 15-1: OUTPUT COMPARE MODES

OCM<2:0>	Mode	OCx Pin Initial State	OCx Interrupt Generation
`000`	Module Disabled	Controlled by GPIO register	—
`001`	Active-Low One-Shot	`0`	OCx rising edge
`010`	Active-High One-Shot	`1`	OCx falling edge
`011`	Toggle	Current output is maintained	OCx rising and falling edge
`100`	Delayed One-Shot	`0`	OCx falling edge
`101`	Continuous Pulse	`0`	OCx falling edge
`110`	PWM without Fault Protection	‘`0`’ if OCxR is zero, ‘`1`’ if OCxR is non-zero	No interrupt
`111`	PWM with Fault Protection	‘`0`’ if OCxR is zero, ‘`1`’ if OCxR is non-zero	OCFA falling edge for OC1 to OC4

FIGURE 15-2: OUTPUT COMPARE OPERATION



REGISTER 21-2: CiCTRL2: ECAN™ CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5	**Unimplemented:** Read as ‘`0`’
bit 4-0	**DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits `10010-11111` = Invalid selection `10001` = Compare up to data byte 3, bit 6 with EID<17> • • • `00001` = Compare up to data byte 1, bit 7 with EID<0> `00000` = Do not compare data bytes

TABLE 23-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	RTSP Effect	Description
SSS<2:0>	FSS	Immediate	Secure Segment Program Flash Code Protection Size bits **(FOR 128K and 256K DEVICES)** `X11` = No secure program Flash segment Secure space is 8K IW less BS: `110` = Standard security; secure program Flash segment starts at end of BS, ends at 0x003FFE `010` = High security; secure program Flash segment starts at end of BS, ends at 0x003FFE Secure space is 16K IW less BS: `101` = Standard security; secure program Flash segment starts at end of BS, ends at 0x007FFE `001` = High security; secure program Flash segment starts at end of BS, ends at 0x007FFE Secure space is 32K IW less BS: `100` = Standard security; secure program Flash segment starts at end of BS, ends at 0x00FFFE `000` = High security; secure program Flash segment starts at end of BS, ends at 0x00FFFE **(FOR 64K DEVICES)** `X11` = No Secure program Flash segment Secure space is 4K IW less BS: `110` = Standard security; secure program Flash segment starts at end of BS, ends at 0x001FFE `010` = High security; secure program Flash segment starts at end of BS, ends at 0x001FFE Secure space is 8K IW less BS: `101` = Standard security; secure program Flash segment starts at end of BS, ends at 0x003FFE `001` = High security; secure program Flash segment starts at end of BS, ends at 0x003FFE Secure space is 16K IW less BS: `100` = Standard security; secure program Flash segment starts at end of BS, ends at 007FFEh `000` = High security; secure program Flash segment starts at end of BS, ends at 0x007FFE
RSS<1:0>	FSS	Immediate	Secure Segment RAM Code Protection bits `11` = No secure RAM defined `10` = Secure RAM is 256 bytes less BS RAM `01` = Secure RAM is 2048 bytes less BS RAM `00` = Secure RAM is 4096 bytes less BS RAM
GSS<1:0>	FGS	Immediate	General Segment Code-Protect bits `11` = User program memory is not code-protected `10` = Standard security; general program Flash segment starts at end of SS, ends at EOM `0x` = High security; general program Flash segment starts at end of SS, ends at EOM

25.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

25.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip’s next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer’s PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

25.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

25.10 PICkit 3 In-Circuit Debugger/Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user’s guide, lessons, tutorial, compiler and MPLAB IDE software.

FIGURE 26-26: CAN MODULE I/O TIMING CHARACTERISTICS

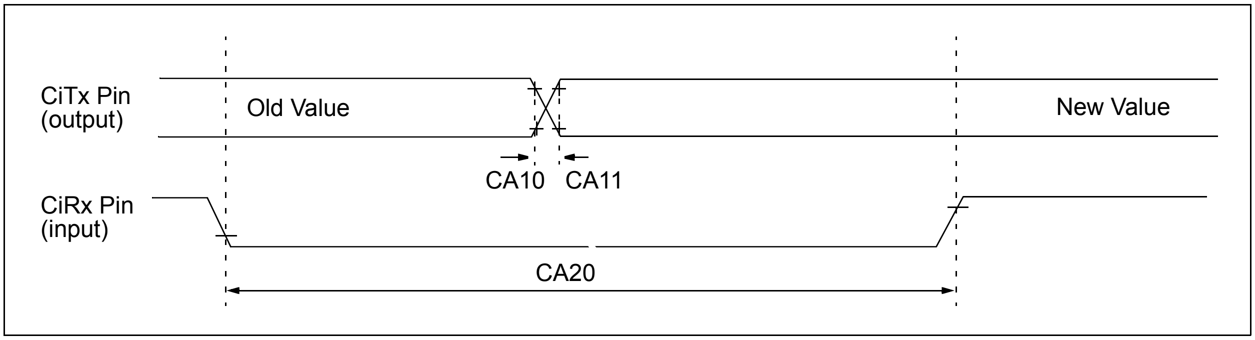
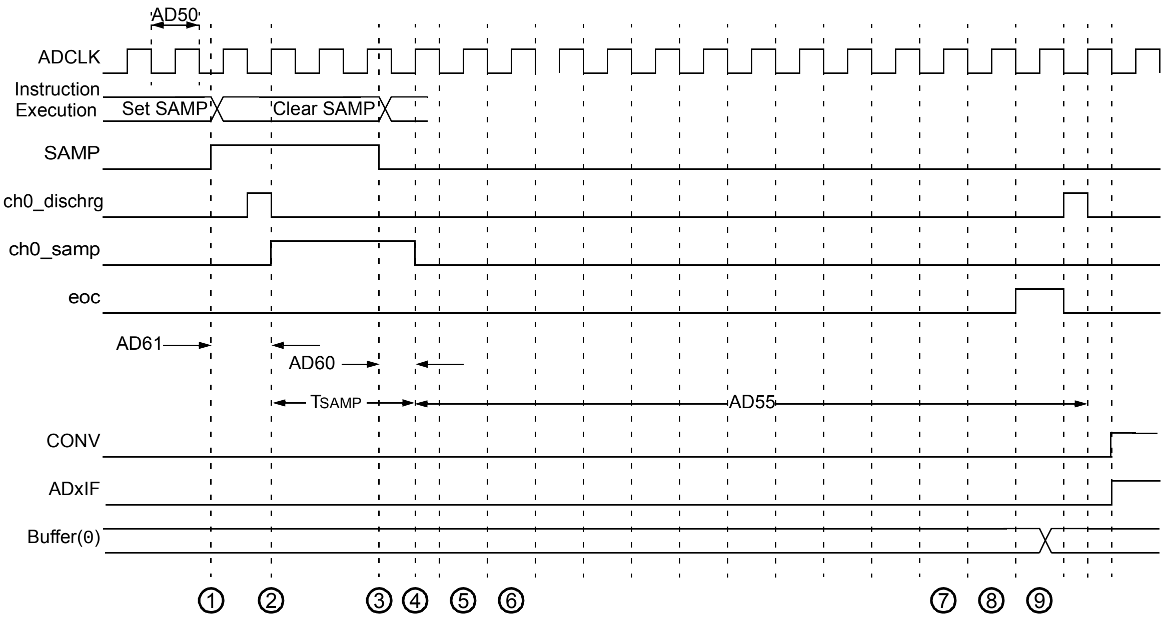


TABLE 26-42: ECAN™ TECHNOLOGY MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
CA10	TioF	Port Output Fall Time	—	—	—	ns	See parameter D032
CA11	TioR	Port Output Rise Time	—	—	—	ns	See parameter D031
CA20	Tcwf	Pulse Width to Trigger CAN Wake-up Filter	120	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 26-27: ADC CONVERSION (12-BIT MODE) TIMING CHARACTERISTICS (ASAM = `0`, SSRC<2:0> = `000`)



① – Software sets ADxCON. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **Section 16. “10/12-bit ADC with DMA”** in the *“dsPIC33F Family Reference Manual”*.

③ – Software clears ADxCON. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

⑤ – Convert bit 11.

⑥ – Convert bit 10.

⑦ – Convert bit 1.

⑧ – Convert bit 0.

⑨ – One TAD for end of conversion.

27.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJXXXMCX06A/X08A/X10A electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 26.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 26.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJXXXMCX06A/X08A/X10A high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(4)	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(5)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V(5)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(5)	-0.3V to 5.6V
Voltage on VCAP with respect to VSS	2.25V to 2.75V
Maximum current out of VSS pin	60 mA
Maximum current into VDD pin(2)	60 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 2x I/O pin(3)	2 mA
Maximum current sourced/sunk by any 4x I/O pin(3)	4 mA
Maximum current sourced/sunk by any 8x I/O pin(3)	8 mA
Maximum current sunk by all ports combined	10 mA
Maximum current sourced by all ports combined(2)	10 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 27-2).

3: Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, VREF+, VREF-, SCLx, SDAx, PGECx, and PGEDx pins.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

5: Refer to the **“Pin Diagrams”** section for 5V tolerant pins.

27.1 High Temperature DC Characteristics

TABLE 27-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)	Temperature Range (in °C)	Max MIPS
			dsPIC33FJXXXMCX06A/X08A/X10A
HDC5	V_{BOR} to 3.6V[1]	-40°C to +150°C	20

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 26-11 for the minimum and maximum BOR values.

TABLE 27-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+155	°C
Operating Ambient Temperature Range	T_A	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $I/O = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 27-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature				
Parameter No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Operating Voltage							
HDC10	**Supply Voltage**						
	V_{DD}	—	3.0	3.3	3.6	V	-40°C to +150°C

TABLE 27-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current[1,3]

Note 1: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to V_{SS}. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 27-17: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	147	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	400	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

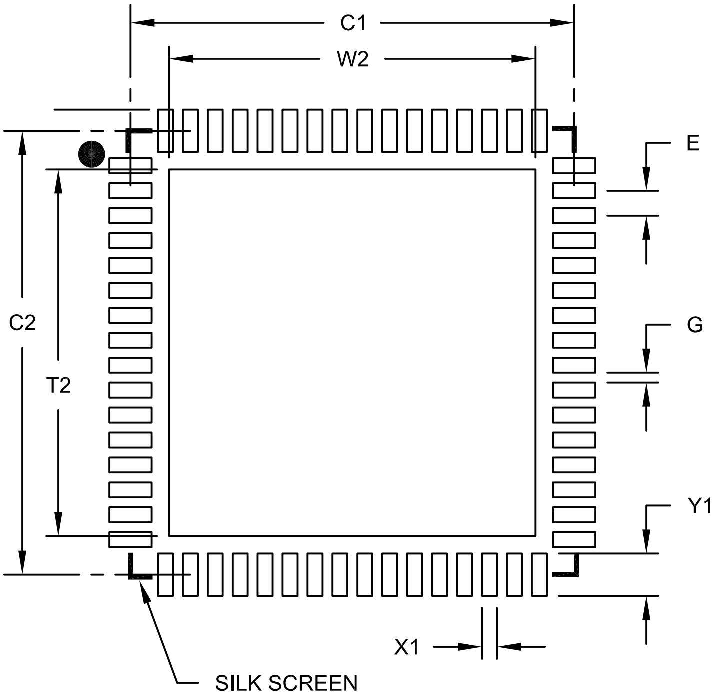
TABLE 27-18: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	104	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	800	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 0.40 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS	
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	W2			7.35
Optional Center Pad Length	T2			7.35
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2149A

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE**.** Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
═ ISO/TS 16949 ═

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC^{32} logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2009-2012, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN: 978-1-62076-343-8

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.